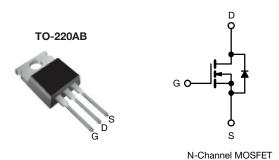
HALOGEN FREE



Power MOSFET



PRODUCT SUMMARY				
V _{DS} (V)	200			
$R_{DS(on)}(\Omega)$	$V_{GS} = 10 \text{ V}$	0.18		
Q _g (Max.) (nC)	70			
Q _{gs} (nC)	13			
Q _{gd} (nC)	39			
Configuration	Single			

FEATURES

- Dynamic dV/dt rating
- · Repetitive avalanche rated
- Fast switching
- · Ease of paralleling
- Simple drive requirements
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

This datasheet provides information about parts that are RoHS-compliant and / or parts that are non RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details



DESCRIPTION

Third generation power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220AB package is universally preferred for all commercial-industrial applications at power dissipation levels to approximately 50 W. The low thermal resistance and low package cost of the TO-220AB contribute to its wide acceptance throughout the industry.

ORDERING INFORMATION			
Package	TO-220AB		
Lead (Pb)-free	IRF640PbF		
Lead (Pb)-free and halogen-free	IRF640PbF-BE3		

PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-source voltage			V _{DS}	200	- v	
Gate-source voltage			V_{GS}	± 20		
Continuous drain current	V _{GS} at 10 V	T _C = 25 °C	,	18	А	
		T _C = 100 °C	I _D	11		
Pulsed drain current ^a			I _{DM}	72		
Linear derating factor				1.0	W/°C	
Single pulse avalanche energy b			E _{AS}	580	mJ	
Repetitive avalanche current a			I _{AR}	18	А	
Repetitive avalanche energy ^a			E _{AR}	13	mJ	
Maximum power dissipation	T _C = 25 °C		P _D	125	W	
Peak diode recovery dV/dt ^c			dV/dt	5.0	V/ns	
Operating junction and storage temperature range			T _J , T _{stg}	-55 to +150	°C	
Soldering recommendations (peak temperature) ^d	For	10 s		300		
Maunting towns	6-32 or M3 screw			10	lbf ⋅ in	
Mounting torque				1.1	N⋅m	

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. V_{DD} = 50 V, starting T_J = 25 °C, L = 2.7 mH, R_g = 25 Ω , I_{AS} = 18 A (see fig. 12) c. I_{SD} \leq 18 A, dI/dt \leq 150 A/µs, V_{DD} \leq V_{DS}, T_J \leq 150 °C d. 1.6 mm from case



Vishay Siliconix

THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum junction-to-ambient	R _{thJA}	-	62		
Case-to-sink, flat, greased surface	R _{thCS}	0.50	-	°C/W	
Maximum junction-to-case (drain)	R _{thJC}	-	1.0		

PARAMETER	SYMBOL	TEST	MIN.	TYP.	MAX.	UNIT	
Static		_		l	•		
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		200	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Reference	Reference to 25 °C, I _D = 1 mA		0.29	-	V/°C
Gate-source threshold voltage	V _{GS(th)}	$V_{DS} = V$	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$		-	4.0	V
Gate-source leakage	I _{GSS}	V _{GS} = ± 20 V		-	-	± 100	nA
		V _{DS} = 2	$V_{DS} = 200 \text{ V}, V_{GS} = 0 \text{ V}$		-	25	μΑ
Zero gate voltage drain current	I _{DSS}	V _{DS} = 160 V, V _{GS} = 0 V, T _J = 125 °C		-	-	250	
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V		-	-	0.18	Ω
Forward transconductance	9fs	V _{DS} = 5	0 V, I _D = 11 A ^b	6.7	-	-	S
Dynamic							
Input capacitance	C _{iss}	$V_{GS} = 0 \text{ V},$ $V_{DS} = 25 \text{ V},$ $f = 1.0 \text{ MHz}, \text{ see fig. 5}$		-	1300	-	pF
Output capacitance	C _{oss}			-	430	-	
Reverse transfer capacitance	C _{rss}			-	130	-	
Total gate charge	Q _g	$V_{GS} = 10 \text{ V}$ $I_D = 18 \text{ A}, V_{DS} = 160 \text{ see fig. 6 and } 13^{10} \text{ see fig. 6}$		-	-	70	nC
Gate-source charge	Q _{gs}		$I_D = 18 \text{ A}, V_{DS} = 160 \text{ V},$	-	-	13	
Gate-drain charge	Q _{gd}		See lig. 6 and 15	-	-	39	
Turn-on delay time	t _{d(on)}	V_{DD} = 100 V, I_{D} = 18 A, R_{g} = 9.1 Ω , R_{D} = 5.4 Ω , see fig. 10 b		-	14	-	- ns
Rise time	t _r			-	51	-	
Turn-off delay time	t _{d(off)}			-	45	-	
Fall time	t _f			-	36	-	
Gate input resistance	L _D	Between lead, 6 mm (0.25") from package and center of die contact		-	4.5	-	- nH
Internal drain inductance	L _S			-	7.5	-	
Internal source inductance	R _g	f = 1 MHz, open drain		0.5	-	3.6	Ω
Drain-Source Body Diode Characteristic	s						
Continuous source-drain diode current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	18	Α
Pulsed diode forward current ^a	I _{SM}			-	-	72	
Body diode voltage	V_{SD}	$T_J = 25 ^{\circ}\text{C}, I_S = 18 \text{A}, V_{GS} = 0 \text{V}^{ \text{b}}$		-	-	2.0	V
Body diode reverse recovery time	t _{rr}	$T_{\rm J} = 25~{\rm ^{\circ}C}, \ I_{\rm F} = 18~{\rm A}, \ dl/dt = 100~{\rm A/\mu s}^{\rm b}$		-	300	610	ns
Body diode reverse recovery charge	Q _{rr}			-	3.4	7.1	μC
Forward turn-on time	t _{on}	Intrinsic turn-on time is negligible (turn-or			minated b	ov L _s and	L _D)

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. Pulse width $\leq 300~\mu s;~duty~cycle \leq 2~\%$



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

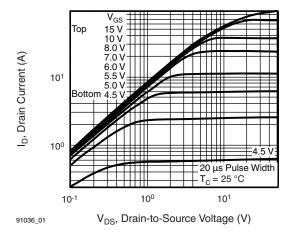


Fig. 1 - Typical Output Characteristics, T_C = 25 °C

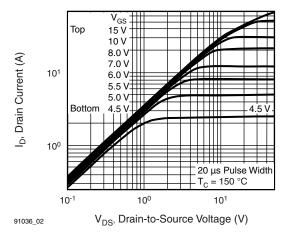


Fig. 2 - Typical Output Characteristics, $T_C = 150 \, ^{\circ}\text{C}$

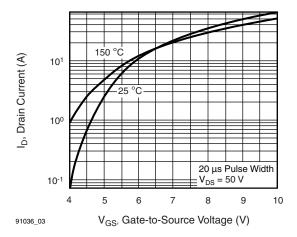


Fig. 3 - Typical Transfer Characteristics

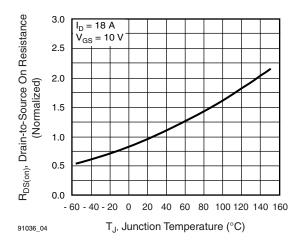


Fig. 4 - Normalized On-Resistance vs. Temperature

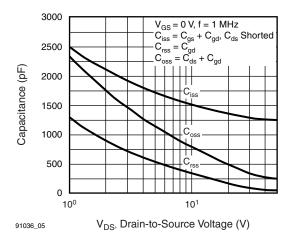


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

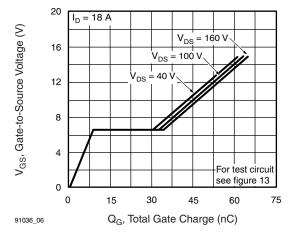


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage



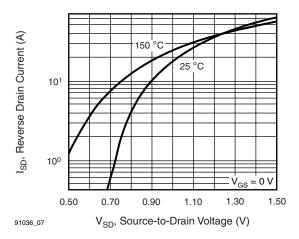


Fig. 7 - Typical Source-Drain Diode Forward Voltage

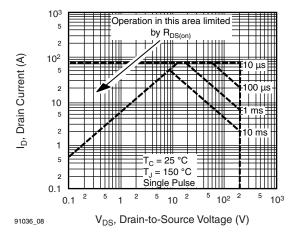


Fig. 8 - Maximum Safe Operating Area

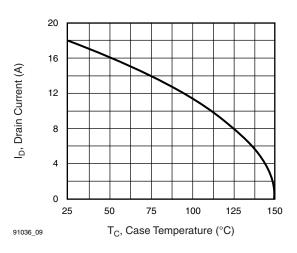


Fig. 9 - Maximum Drain Current vs. Case Temperature

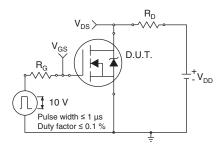


Fig. 10a - Switching Time Test Circuit

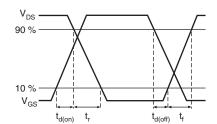


Fig. 10b - Switching Time Waveforms

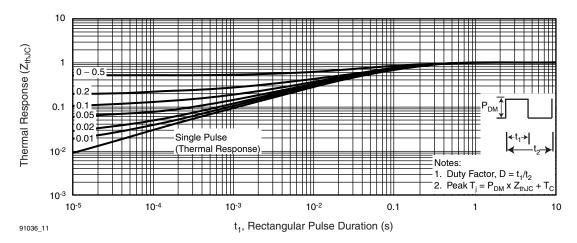


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case



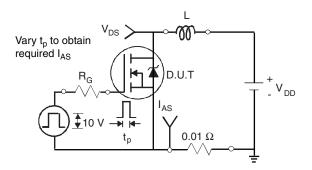


Fig. 12a - Unclamped Inductive Test Circuit

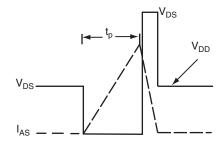


Fig. 12b - Unclamped Inductive Waveforms

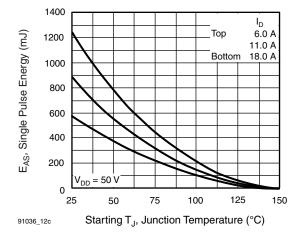


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

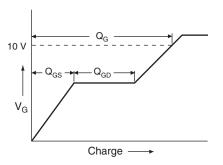


Fig. 13a - Basic Gate Charge Waveform

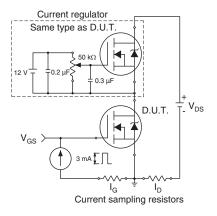
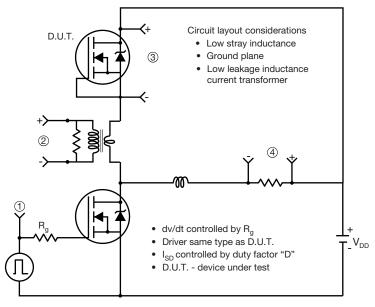


Fig. 13b - Gate Charge Test Circuit



Peak Diode Recovery dv/dt Test Circuit



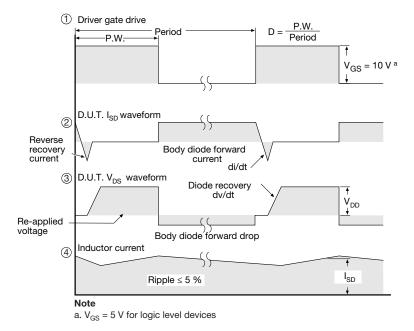


Fig. 14 - For N-Channel

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